



# Product Change Notification

**Change Notification #: 114638 - 00**

**Change Title:** Intel® SSD DC S3510 Series  
(240GB, 2.5in SATA 6Gb/s, 16nm, MLC) 7mm, Generic Single Pack,  
Intel® SSD DC S3510 Series  
(240GB, 2.5in SATA 6Gb/s, 16nm, MLC) 7mm, Generic 50 Pack,  
Intel® SSD DC S3610 Series  
(200GB, 1.8in SATA 6Gb/s, 20nm, MLC) 7mm, Generic Single Pack,  
Intel® SSD DC S3610 Series  
(200GB, 1.8in SATA 6Gb/s, 20nm, MLC) 7mm, Generic 50 Pack,  
Intel® SSD DC S3610 Series  
(200GB, 2.5in SATA 6Gb/s, 20nm, MLC) 7mm, Generic Single Pack,  
Intel® SSD DC S3610 Series  
(200GB, 2.5in SATA 6Gb/s, 20nm, MLC) 7mm, Generic 50 Pack,  
Intel® SSD DC S3710 Series  
(200GB, 2.5in SATA 6Gb/s, 20nm, MLC) 7mm, Generic Single Pack,  
Intel® SSD DC S3710 Series  
(200GB, 2.5in SATA 6Gb/s, 20nm, MLC) 7mm, Generic 50 Pack,  
PCN 114638-00, Product Material,  
Adding alternate DRAM to Bill of Materials

**Date of Publication:** May 24, 2016

**Key Characteristics of the Change:**

Product Material

**Forecasted Key Milestones:**

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Jun 23, 2016
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### **Description of Change to the Customer:**

The following changes have been made to the Intel® SSD DC S3510 Series, Intel® SSD DC S3610 Series and Intel® SSD DC S3710 Series products listed on the Products Affected/Intel Ordering Codes table:

1. Added Micron 20nm x8 4G DRAM (IPN: H95383-001) as an alternate
2. Current HV3/HV10 (200G) use Micron 30nm x8 4G DRAM (IPN: G50546-001)
3. Current HVSE (240G) use Micron 25nm x8 4G DRAM (IPN: H67365-001)

These changes do not change the form, fit, function, visual or reliability of the product.

### **Customer Impact of Change and Recommended Action:**

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

### **Products Affected / Intel Ordering Codes:**

<b>Product Code</b>	<b>MM#</b>
SSDSC2BA200G401	937741
SSDSC2BA200G4	937742
SSDSC1BG200G401	939145
SSDSC1BG200G4	939146
SSDSC2BX200G4	940778
SSDSC2BX200G401	940779
SSDSC2BB240G601	941813
SSDSC2BB240G6	941814

### **PCN Revision History:**

**Date of Revision:**

May 24, 2016

**Revision Number:**

00

**Reason:**

Originally Published PCN



# Product Change Notification

## 114638 - 00

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

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